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U.S. UTILITY Patent Application

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**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/03891 06/15/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 172821/1999 06/18/1999 JAPAN 204842/1999 07/19/1999 JAPAN 332221/1999 11/24/1999					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 511.40998X00	
Verified and Acknowledged Examiners's initials					
TITLE : Abrasive compound for cmp, method for polishing substrate and method for manufacturing semiconductor device using the same, and additive for cmp abrasive compound					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs.Drwg.
Primary Examiner		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
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